

Title (en)

METHOD FOR PRODUCING MICROMECHANIC SENSORS AND SENSORS PRODUCED BY SAID METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG VON MIKROMECHANISCHEN SENSOREN UND DAMIT HERGESTELLTE SENSOREN

Title (fr)

PROCEDE DE PRODUCTION DE DETECTEURS MICROMECHANIQUES, ET DETECTEURS AINSI OBTENUS

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Application

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Abstract (en)

[origin: WO02076880A2] The invention relates to a method for producing micromechanic sensors, and the sensors produced thereby, in which openings (2) are made in a semiconductor substrate (1). A subsequent temperature treatment is carried out after the openings (2) have been made in the semiconductor substrate (1), converting said openings (2) into cavities in the depth of the substrate (1).

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